# **PRODUCT SPECIFICATION**





- < >> Preliminary Specification
- < ◆> Finally Specification

	CUSTOMER'S APPROVAL							
CUSTOMER:	CUSTOMER:							
SIG	NATURE:	DATE:						

APPROVED	PM	PD	PREPARED
ВҮ	REVIEWED	REVIEWED	BY
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knitter-switch

# **Revision History**

Revision	Date	Originator	Detail	Remarks
1.0	2024.01.02	DFG	Initial Release	

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## 1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

#### 2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	5.7"	
LCD type	IPS TFT	
Display Mode	Normal Black/Transmissive	
Resolution	720 RGB x 1440	Pixels
View Direction	Full view	Best Image
Module Outline	67.12 (H) x 136.4(V) x 2.09(T) (Note1)	mm
Active Area	64.8(H) x 129.6(V)	mm
Pixel Size	90 (H) x 90(V)	um
Pixel Arrangement	RGB Vertical Stripe	
Polarizer Surface Treatment	Glare	
Display Colors	16.7M	
Driver IC	ILI9881C-05	-
Interface	4 Lane MIPI	
With or Without Touch Panel	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	44	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

## 3. Absolute Maximum Ratings

GND=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	-0.3	7.0	V
Storage temperature	T <sub>STG</sub>	-30	80	°C
Operating temperature	T <sub>OP</sub>	-20	70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

## 4. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage	VDD	2.5	3.3	6.6	V
Logic Low input voltage	V <sub>IL</sub>	-0.3	-	0.3*VDD	V
Logic High input voltage	V <sub>IH</sub>	0.7*VDD	-	VDD	V
Output low voltage	V <sub>OL</sub>	0	-	0.2*VDD	V
Output high voltage	V <sub>OH</sub>	0.8*VDD	-	VDD	V
Current Consumption All white	IDD	-	31	-	mA

# 5. Backlight Characteristics

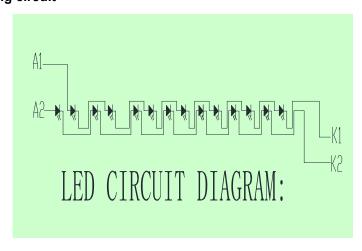
## 5.1. Backlight Characteristics

Item	Symbol Condition		Min.	Тур.	Max.	Unit
Backlight Voltage	VLED	Ta=25 °C, I <sub>F</sub> =20mA/LED	18.9	21	22.4	V
Backlight Current	ILED	Ta=25 °C, V <sub>F</sub> =3.0V/LED	-	40	-	mA
Power dissipation	PD		-	840	-	mW
Uniformity	Avg		-	80	-	%
LED working life(25℃)	-		-	30,000	-	Hrs
Drive method	Constant current					
LED Configuration	14 \	White LEDs (7 LEDs in one	string an	d 2 groups	in paral	lel)

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25  $\pm 2$  °C,60%RH  $\pm 5$ %, I<sub>F</sub>=20mA/LED.

## 5.2. Backlighting circuit



# 6. Optical Characteristics

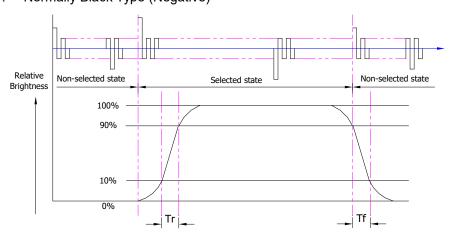
## 6.1. Optical Characteristics

Ta=25°C, VDD=3.3V

	Item		Symbol	Condition	Sı	oecificatio	on	Unit		
	iten		Symbol	Condition	Min.	Тур.	Max.	Ullit		
	Luminance on									
(a)	$TFT(I_f \texttt{=} 20 r$	mA/LED)	Lv	Normally	240	300	-	cd/m²		
po	Contrast ratio	(See 6.3)	CR	viewing angle	800	1000	-			
Backlight On (Transmissive Mode)	i i	Response time (See 6.2)		$\theta x = \phi Y = 0^{\circ}$	$\theta x = \phi Y = 0^{\circ}$	$\theta x = \phi Y = 0^{\circ}$		30	35	ms
Sm		Dod	XR		0.603	0.653	0.703			
ran		Red	YR		0.297	0.347	0.397			
ا ك	Chromoticity	Chromaticity Green	Xg		0.269	0.319	0.369			
Ö	Transmissive		YG		0.600	0.650	0.700			
ght	(See 6.5)	Blue	Хв		0.085	0.147	0.197			
불	(000 0.0)	blue	YB		0.072	0.122	0.172			
Ba		White	Xw		0.272	0.322	0.372			
		VVIIILE	Yw		0.325	0.375	0.425			
		Horizontal	θx+		80	85	-			
	Viewing Angle (See 6.4)	TIONZONIA	θх-	Center CR≥10	80	85	-	Dog		
		Vertical	φY+	Center CR210	80	85	-	Deg.		
		VEHILLAI	φY-		80	85	-			
	NST	2		Θ=0°	65	70	-	%		

## 6.2. Definition of Response Time

### 6.2.1. Normally Black Type (Negative)



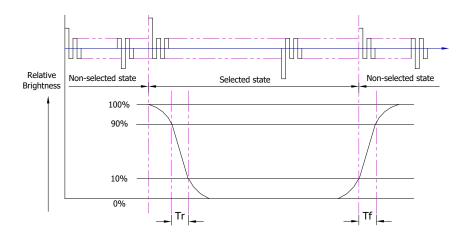
Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to

non-selected state with relative luminance 10%

Note: Measuring machine: LCD-5100

### 6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

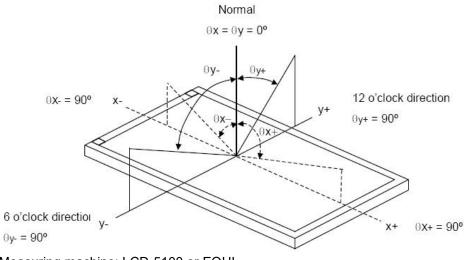
#### 6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent		
Measuring Point Diameter	3mm//1mm		
Measuring Point Location	Active Area centre point		
Test nettern	A: All Pixels white		
Test pattern	B: All Pixel black		
Contrast setting	Maximum		

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

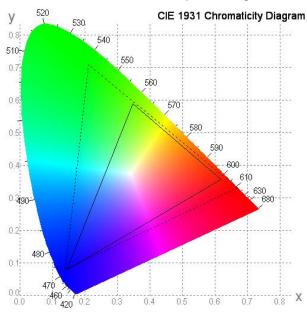
#### 6.4. Definition of Viewing Angles



### 6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

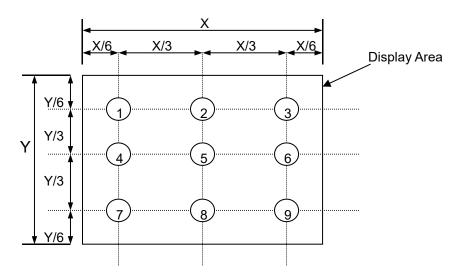


### 6.6. Definition of Surface Luminance, Uniformity and Transmittance

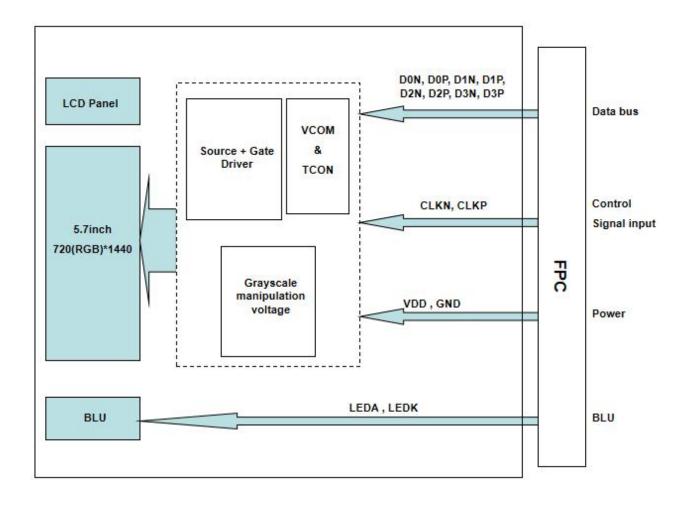
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance:  $L_V$  = average ( $L_{P1}$ : $L_{P9}$ )
- 6.6.2. Uniformity = Minimal  $(L_{P1}:L_{P9})$  / Maximal  $(L_{P1}:L_{P9})$  \* 100%
- 6.6.3. Transmittance =  $L_V$  on LCD /  $L_V$  on Backlight \* 100%

Note: Measuring machine: BM-7



# 7. Block Diagram and Power Supply

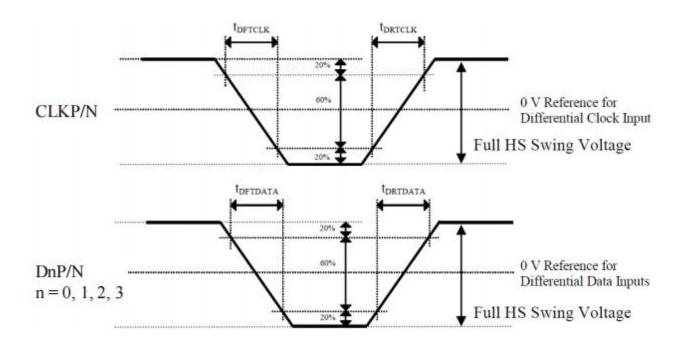


# 8. Interface Pins Definition

No.	Symbol	Function
1	LEDA	LED Anode
2	LEDA	LED Anode
3	LEDK	LED Cathode
4	LEDK	LED Cathode
5	VDD	Power supply
6	GND	Ground
7	D0N	Data signal negative
8	D0P	Data signal positive
9	GND	Ground
10	D1N	Data signal negative
11	D1P	Data signal positive
12	GND	Ground
13	CLKN	Clock signal negative
14	CLKP	Clock signal positive
15	GND	Ground
16	D2N	Data signal negative
17	D2P	Data signal positive
18	GND	Ground
19	D3N	Data signal negative
20	D3P	Data signal positive
21	GND	Ground
22	NC(XR)	No connection
23	NC(YD)	No connection
24	NC(XL)	No connection
25	NC(YU)	No connection
26	GND	Ground
27	GND	Ground
28	GND	Ground
29	GND	Ground
30	GND	Ground

## 9. AC Characteristics

## 9.1. High Speed Mode - Rising and Falling Timings

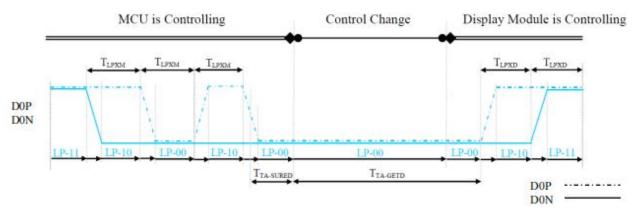


	Cumbal	0	Specification		
Parameter	Symbol	Condition	Min	Тур	Max
Differential Rise Time for Clock	torrack	CLKP/N	150 ps	-	0.3UI (Note)
Differential Rise Time for Data	t <sub>DRTDATA</sub>	DnP/N n=0 and 1	150 ps	-	0.3UI (Note)
Differential Fall Time for Clock	t <sub>DFTOLK</sub>	CLKP/N	150 ps	-	0.3UI (Note)
Differential Fall Time for Data	TOFTDATA	DnP/N n=0 and 1	150 ps		0.3UI (Note)

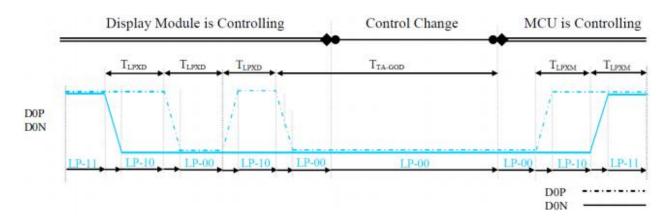
**Note:** The display module has to meet timing requirements, which are defined for the transmitter (MCU) on MIPI D-Phy standard.

### 9.2. Low Speed Mode - Bus Turn Around

## 9.2.1. BTA from the MCU to the Display Module



## 9.2.2. BTA from the Display Module to the MCU



## 10. Quality Assurance

### 10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

#### 10.2. Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5.

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

#### 10.3. Nonconforming Analysis & Disposition

- 10.3.1. Nonconforming analysis:
  - 10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
  - 10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
  - 10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.
- 10.3.2. Disposition of nonconforming:
  - 10.3.2.1. Non-conforming product over PPM level will be replaced.
  - 10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

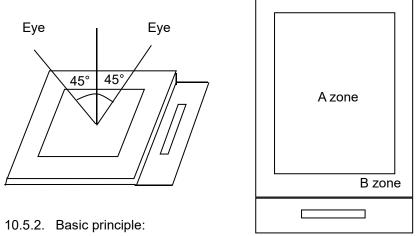
#### 10.4.Agreement Items

Shall negotiate with customer if the following situation occurs:

- 10.4.1. There is any discrepancy in standard of quality assurance.
- 10.4.2. Additional requirement to be added in product specification.
- 10.4.3. Any other special problem.

#### 10.5. Standard of the Product Visual Inspection

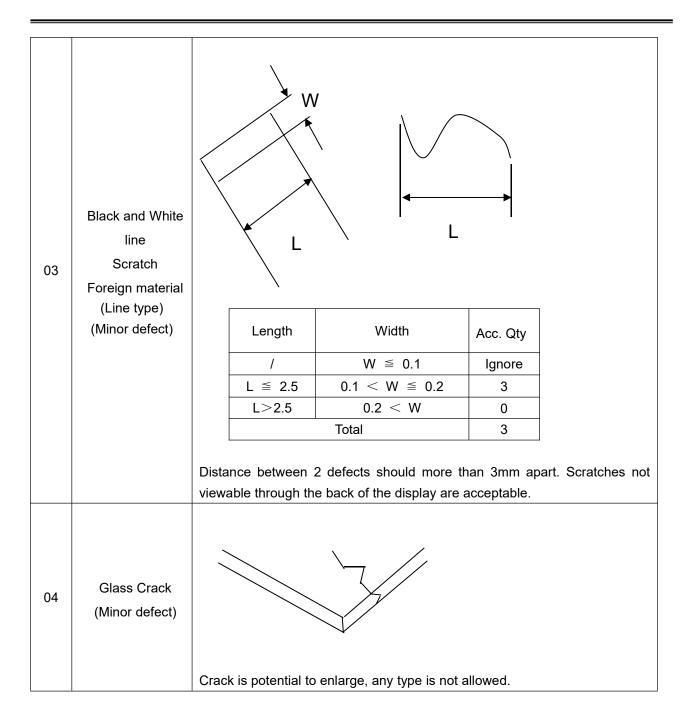
- 10.5.1. Appearance inspection:
  - 10.5.1.1. The inspection must be under illumination about  $1000 1500 \, \text{lx}$ , and the distance of view must be at  $30 \, \text{cm} \pm 2 \, \text{cm}$ .
  - 10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.
  - 10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,

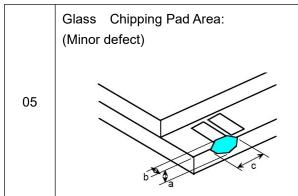


10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.10.5.2.2. New item must be added on time when it is necessary.

## 10.6.Inspection Specification

No.	Item	Criteria (Unit: mm)				
01	Black / White spot Foreign material (Round type) Pinholes	a	Size φ≤0 0.20<ψ	0.20 I p≤0.50	cc. Qty gnore N≤3	
	Stain Particles inside cell. (Minor defect)	$\begin{array}{c c} & 0.50 < \phi & 0 \\ \hline \\ \phi = (a+b)/2 \\ \hline \\ \text{Distance between 2 defects should more than 5mm apart.} \end{array}$				
02	Electrical Defect (Minor defect)	Dark dot N≤4 N≤4		N≤2 N≤4 N≤4 gh 5% ND filters.	Note 1 Note 2 Do item 1.	





Length and Width	Acc. Qty	
c > 3.0, b< 1.0	1	
c< 3.0, b< 1.0	3	
a <glass td="" thickness<=""></glass>		

	Glass Chipping Rear of Pad Area:			
06	(Minor defect)	Length and Width	Acc. Qty	
		c > 3.0, b< 1.0	1	
		c< 3.0, b< 1.0	2	
		c< 3.0, b< 0.5	4	
	c	a <glass td="" thickness<=""></glass>		
	b ga			
	Glass Chipping Except Pad Area: (Minor defect)			
		Length and Width	Acc. Qty	
0.7		c > 3.0, b< 1.0	1	
07		c< 3.0, b< 1.0	2	
	b	c< 3.0, b< 0.5	4	
	The state of the s	a <glass td="" thick<=""><td>ness</td></glass>	ness	
	a 🏲			
	Glass Corner Chipping: (Minor defect)		A	
		Length and Width	Acc. Qty	
08		c < 3.0, b< 3.0 a <glass td="" thick<=""><td>Ignore</td></glass>	Ignore	
08	barocc	a voidos Tillor	WI1033	
	Glass Burr:			
	(Minor defect)	Length	Acc. Qty	
		F < 1.0	Ignore	
09	F	Glass burr don't affect assemble and module dimension.		
	- F			

	<u> </u>					
	FPC Defect:					
	(Minor defect)					
10	2; ;		10.1 Dent, pinhole	10.1 Dent, pinhole width a <w 3.<="" td=""></w>		
	$w \rightarrow 0$		(w: circuitry width.)	(w: circuitry width.)		
			10.2 Open circuit is	unacceptable.		
			10.3 No oxidation,	contamination an	d distortion.	
			Diameter	Acc. Qty		
			φ≤0.30	Ignore		
11	Bubble on Polarizer		0.30 <φ≤0.50	N≤2		
	(Minor defect)		0.50 < φ	N=0		
			υ.ου τ φ			
			D'	A Ot .		
	Dent on Polarizer (Minor defect)		Diameter	Acc. Qty		
12			φ≤0.25	Ignore		
12			0.25 <φ≤0.50	N≤4		
			0.50 < φ	None		
		40.4 No	andina na dha Danal			
13	Bezel	13.1 No rust, distortion on the Bezel.				
		13.2 No visible fingerprints, stains or other contamination.				
		14.1 No distortion	n or contamination on P	CB terminals.		
	РСВ	14.2 All components on PCB must same as documented on the				
14		BOM/component layout.				
			-			
		14.3 Follow IPC-A-600F.				
15	Soldering	Follow IPC-A-610C standard				
		The below defect	ts must be rejected.			
			cal / horizontal segment,			
			onormal Display.			
		16.3 No function or no display.				
16						
	(Major defect)					
16	Electrical Defect (Major defect)	<ul><li>16.3 No function or no display.</li><li>16.4 Current exceeds product specifications.</li><li>16.5 LCD viewing angle defect.</li><li>16.6 No Backlight.</li><li>16.7 Dark Backlight.</li></ul>				
	16.8 Touch Panel no function.					

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

#### 10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

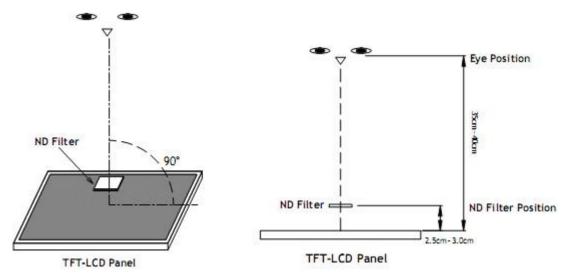
#### 10.8.Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

#### 10.9. Packing

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

**Note2:** Mura on display which appears darker / brighter against background brightness on parts of display area.

# 11. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	<b>70℃</b> , 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50℃, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-20℃, 60min ~ 70℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: $\pm$ 4KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.2 -2018
		Contact: $\pm$ 2KV 150pF/330 $\Omega$ 5 times		
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

## 12. Precautions and Warranty

#### 12.1.Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

#### 12.2. Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

#### 12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

## 12.4. Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting

Solder Pin Lead

Recommended

Solder Pin Lead

Not Recommended

#### 12.4.2. Pins of EL

12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

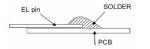
Typical Soldering Time: ≤2s

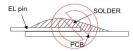
Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

#### 12.4.2.6. Solder Wetting





Recommended

Not Recommended

12.4.2.7. The type of the solder iron:





Recommended

Not Recommended

12.4.2.8. Solder Pad



#### 12.5. Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

#### 12.6. Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

#### 12.7.Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

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**TBD** 

## 14. Outline Drawings

